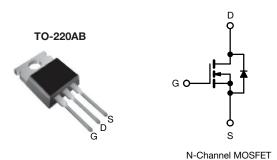


Power MOSFET



PRODUCT SUMMARY				
V _{DS} (V)	400 V			
$R_{DS(on)}(\Omega)$	V _{GS} = 10 V	1.8		
Q _g max. (nC)	20			
Q _{gs} (nC)	3.3			
Q _{gd} (nC)	11			
Configuration	Single			

FEATURES

- Dynamic dV/dt rating
- Repetitive avalanche rated
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRF720PbF		
Lead (Pb)-free and halogen-free	IRF720PbF-BE3		

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	400	V	
Gate-source voltage			V_{GS}	± 20	V	
Continuous drain current	V _{GS} at 10 V	_c = 25 °C	I-	3.3	А	
	V _{GS} at 10 V	= 100 °C	I _D	2.1		
Pulsed drain current a			I _{DM}	13		
Linear derating factor				0.40	W/°C	
Single pulse avalanche energy b			E _{AS}	190	mJ	
Repetitive avalanche current a			I _{AR}	3.3	А	
Repetitive avalanche energy ^a			E _{AR}	5.0	mJ	
Maximum power dissipation	T _C = 25 °C		P_{D}	50	W	
Peak diode recovery dV/dt ^c			dV/dt	4.0	V/ns	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) ^d	For 10 s	;	-	300		
Mounting torque	6-32 or M3 screw			10	lbf ⋅ in	
				1.1	N · m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 30 mH, R_q = 25 Ω , I_{AS} = 3.3 A (see fig. 12)
- c. $I_{SD} \le 3.3$ A, $dI/dt \le 65$ A/µs, $V_{DD} \le V_{DS}$, $T_J \le 150$ °C
- d. 1.6 mm from case



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	-	62		
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W	
Maximum junction-to-case (drain)	R _{thJC}	-	2.5		

PARAMETER	SYMBOL	TEST	MIN.	TYP.	MAX.	UNIT	
Static				1		1	
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA		400	_	_	V
		40	GG / B		0.51	_	V/0C
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I _D = 1 mA	-	0.51	_	V/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		-	4.0	V
Gate-source leakage	I _{GSS}	V	$_{GS} = \pm 20$	-	-	± 100	nA
Zero gate voltage drain current	I _{DSS}	V _{DS} = 400 V, V _{GS} = 0 V		-	-	25	μA
Zero gate voltage drain danem	פטי	$V_{DS} = 320 \text{ V}, \text{ V}$	$I_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$	- .	-	250	μΛ
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	$I_D = 2.0 \text{ A}^{\text{ b}}$	-	-	1.8	Ω
Forward transconductance	9fs	$V_{DS} = 50$	0 V, I _D = 2.0 A ^b	1.7	-	-	S
Dynamic				•	•	•	•
Input capacitance	C _{iss}	$V_{GS} = 0 V$		-	410	-	pF
Output capacitance	C _{oss}	V	$V_{DS} = 25 \text{ V},$		120	-	
Reverse transfer capacitance	C _{rss}	f = 1.0 l	MHz, see fig. 5	-	47	-	1
Total gate charge	Q_g	I _D = 3.3 A,	-	-	20		
Gate-source charge	Q_{gs}	V _{GS} = 10 V	V _{DS} = 320 V, see fig. 6 and 13 b	-	-	3.3	nC
Gate-drain charge	Q _{gd}			-	-	11	
Turn-on delay time	t _{d(on)}			-	10	-	
Rise time	t _r	V_{DD} = 200 V, I_{D} = 3.3 A R_{g} = 18 Ω , R_{D} = 56 Ω , see fig. 10 ^b		-	14	-	ns
Turn-off delay time	t _{d(off)}			-	30	-	
Fall time	t _f	1			13	-	
Gate input resistance	R_{g}	f = 1 MHz, open drain		1.2	-	7.3	Ω
Internal drain inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	- nH
Internal source inductance	L _S			-	7.5	-	
Drain-Source Body Diode Characteristic	cs			L			
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	3.3	А
Pulsed diode forward current ^a	I _{SM}			_	-	13	
Body diode voltage	V _{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 3.3 \text{A}, V_{GS} = 0 \text{V}^{ \text{b}}$		-	-	1.6	V
Body diode reverse recovery time	t _{rr}	T _J = 25 °C, I _F = 3.3 A, dl/dt = 100 A/μs b		-	270	600	ns
Body diode reverse recovery charge	Q_{rr}			-	1.4	3.0	μC
Forward turn-on time	t _{on}	Intrinsic turn	on time is negligible (turr	-on is do	minated b	y L _S and	L _D)

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width \leq 300 µs; duty cycle \leq 2 %



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

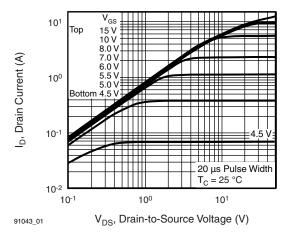


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

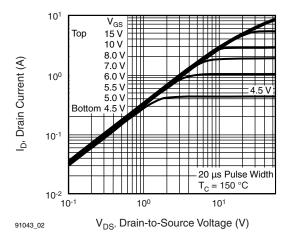


Fig. 2 - Typical Output Characteristics, $T_C = 150$ °C

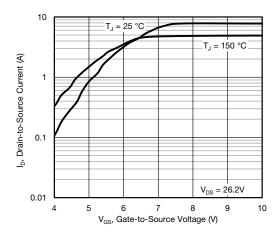


Fig. 3 - Typical Transfer Characteristics

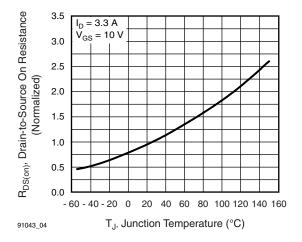


Fig. 4 - Normalized On-Resistance vs. Temperature

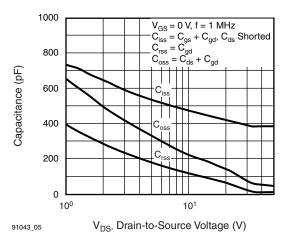


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

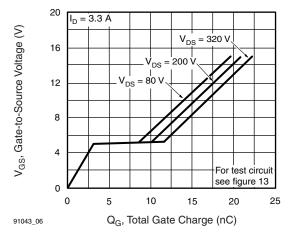


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



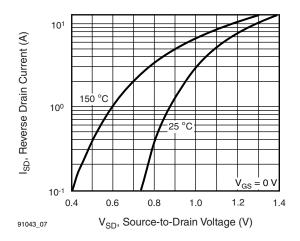


Fig. 7 - Typical Source-Drain Diode Forward Voltage

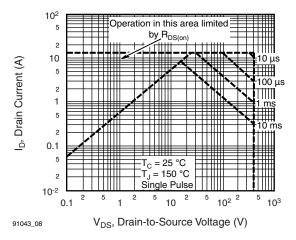


Fig. 8 - Maximum Safe Operating Area

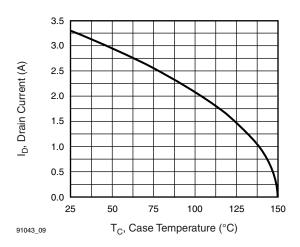


Fig. 9 - Maximum Drain Current vs. Case Temperature

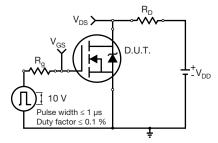


Fig. 10a - Switching Time Test Circuit

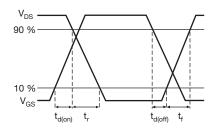


Fig. 10b - Switching Time Waveforms

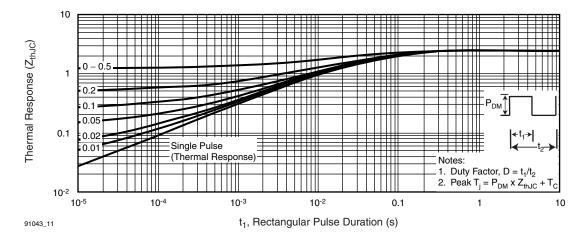




Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

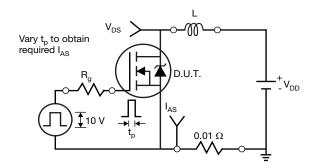


Fig. 12a - Unclamped Inductive Test Circuit

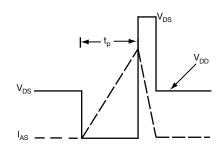


Fig. 12b - Unclamped Inductive Waveforms

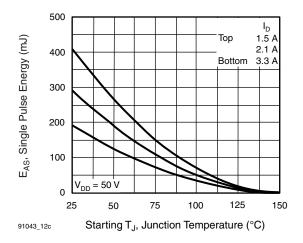


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

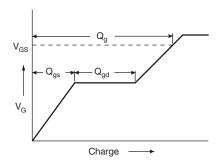


Fig. 13a - Basic Gate Charge Waveform

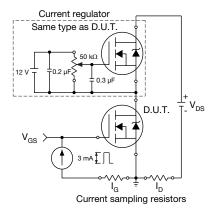
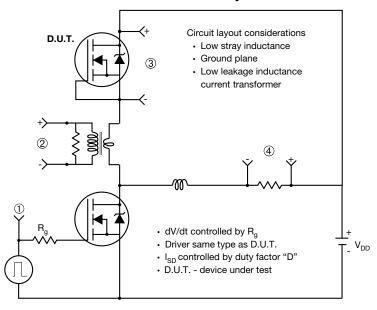


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



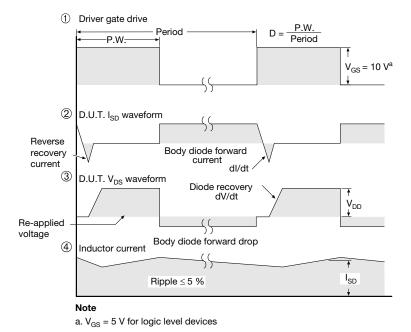


Fig. 14 - For N-Channel

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